

Features

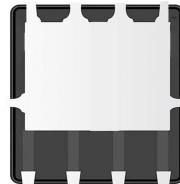
- Trench LV MOSFET technology
- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity

Product Summary

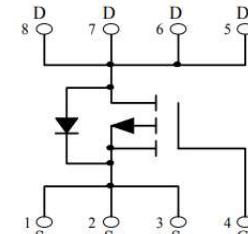
V_{DS}	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
-20V	20mΩ@-4.5V	-25A
	25mΩ@-2.5V	

Application

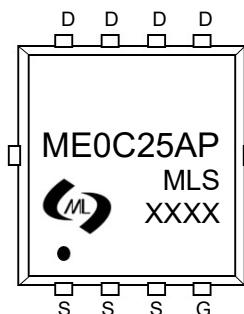
- Power management
- Portable equipment



PDFN3X3-8L view



Schematic diagram



Marking and pin assignment

ME0C25AP: Device code
XXXX : Code


Halogen-Free

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit	
Common Ratings (TC=25°C Unless Otherwise Noted)				
V_{DS}	Drain-Source Breakdown Voltage	-20	V	
V_{GS}	Gate-Source Voltage	± 10	V	
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-50 to 155	°C	
I_S	Diode Continuous Forward Current	Tc=25°C	-25	A
Mounted on Large Heat Sink				
I_{DM}	Pulse Drain Current Tested	Tc=25°C	-116	A
I_D	Continuous Drain Current	Tc=25°C	-25	A
P_D	Maximum Power Dissipation	Tc=25°C	26	W
$R_{θJA}$	Thermal Resistance Junction-Ambient		10.5 °C/W	

Ordering Information (Example)

Type	Package	Marking	Minimum Package(pcs)	Inner Box Quantity(pcs)	Outer Carton Quantity(pcs)	Delivery Mode
ME0C25AP	PDFN3X3-8L	ME0C25AP	5,000	10,000	70,000	13" reel

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
BV _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V	--	--	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.58	-1.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-20A	--	12	20	mΩ
		V _{GS} =-2.5V, I _D =-10A	--	15	25	mΩ

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

C _{ISS}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz	--	2995	--	pF
C _{OSS}	Output Capacitance		--	330	--	pF
C _{RSS}	Reverse Transfer Capacitance		--	270	--	pF

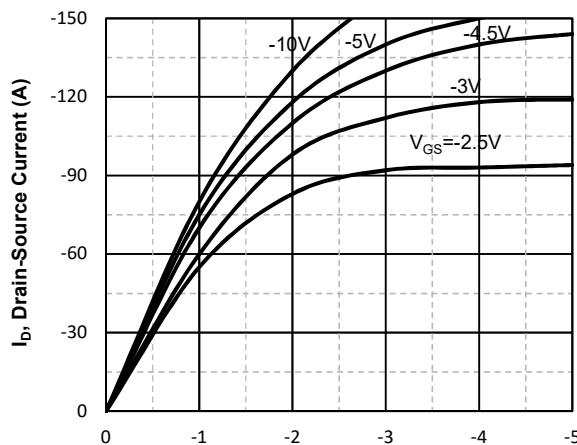
Switching Characteristics

Q _g	Total Gate Charge	V _{DS} =-10V, I _D =-20A, V _{GS} =-9V	--	73	--	nC
Q _{gs}	Gate Source Charge		--	6.5	--	nC
Q _{gd}	Gate Drain Charge		--	10	--	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =-10V, I _D =-20A, V _{GS} =-10V, R _G =3Ω	--	7	--	nS
t _r	Turn-on Rise Time		--	33	--	nS
t _{d(off)}	Turn-Off Delay Time		--	130	--	nS
t _f	Turn-Off Fall Time		--	135	--	nS

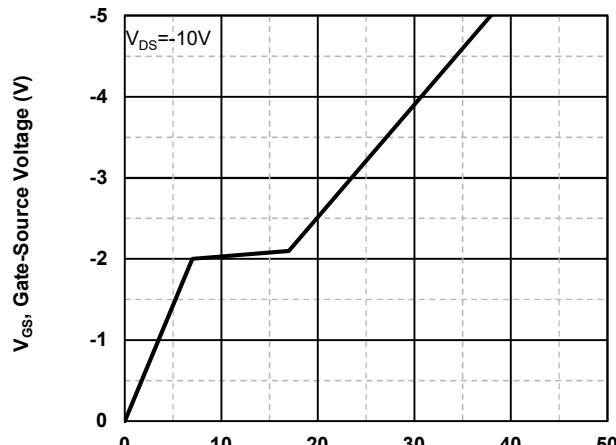
Source-Drain Diode Characteristics

V _{SD}	Forward on voltage	T _J =25°C, I _S =-20A	--	-0.8	-1.2	V
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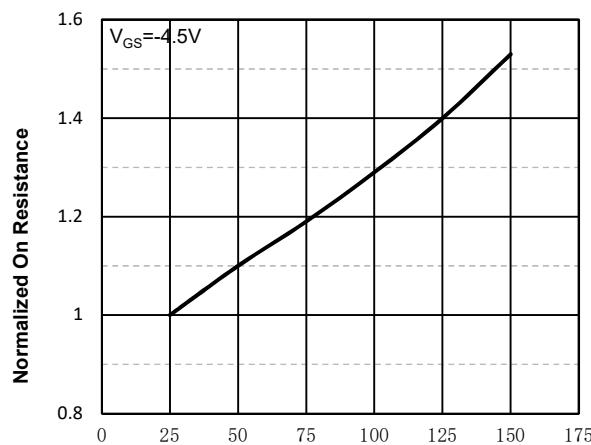
Typical Operating Characteristics



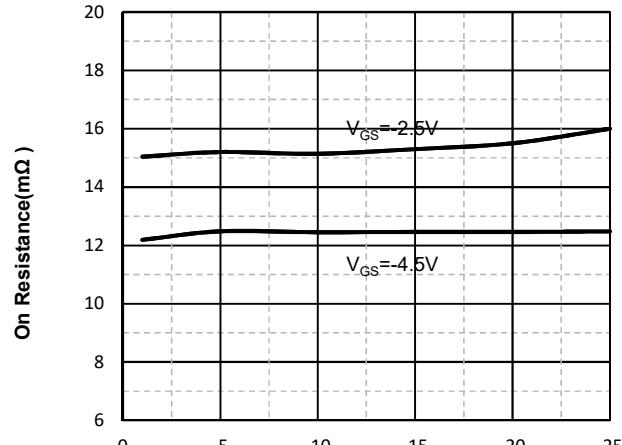
V_{DS} , Drain -Source Voltage (V)
Fig1. Typical Output Characteristics



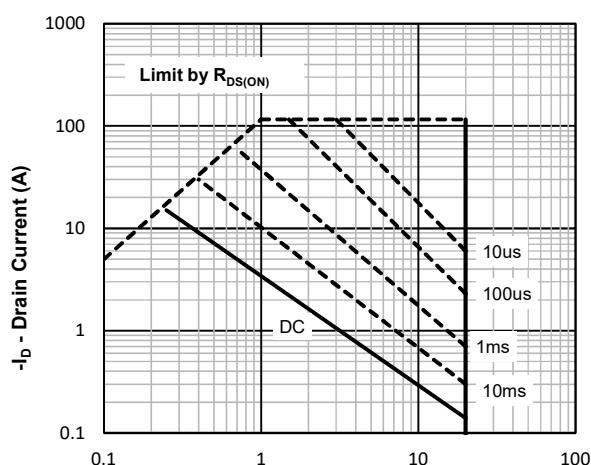
Q_g -Total Gate Charge (nC)
Fig2. Typical Gate Charge Vs.Gate-Source Voltage



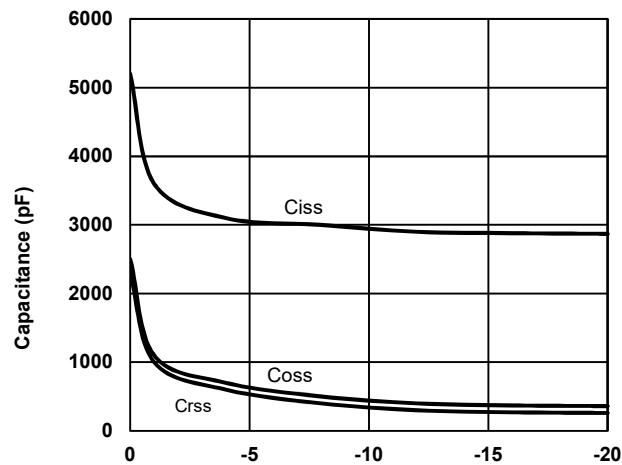
T_j - Junction Temperature (°C)
Fig3. Normalized On-Resistance Vs. Temperature



I_D , Drain-Source Current (A)
Fig4. On-Resistance Vs. Drain-Source Current

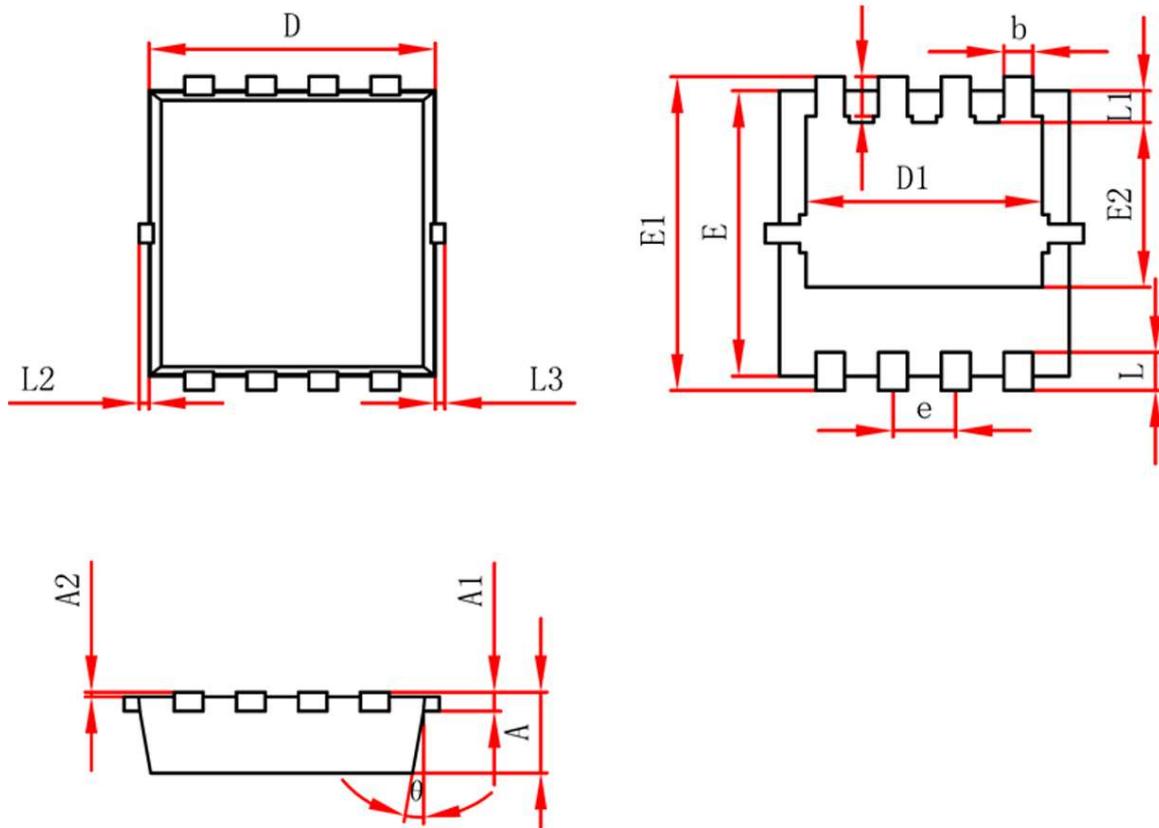


- V_{DS} , Drain -Source Voltage (V)
Fig5. Maximum Safe Operating Area



V_{DS} , Drain-Source Voltage (V)
Fig6 Typical Capacitance Vs.Drain-Source Voltage

PDFN3X3-8L Package information



Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	0.750	0.850	0.030	0.034
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.950	3.150	0.117	0.125
D1	2.400	2.500	0.095	0.099
E	2.950	3.050	0.117	0.121
E1	3.250	3.350	0.129	0.132
E2	1.685	1.785	0.067	0.071
b	0.250	0.350	0.010	0.014
e	0.600	0.700	0.024	0.028
L	0.350	0.450	0.014	0.018
L1	0.325	0.425	0.013	0.017
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.365	0.465	0.014	0.018
θ	10°	12°	10°	12°